

GL SiC Schottky Diode

General Description :

GL10G1200B47 Schottky Diode from MacMic utilizes advanced processing techniques to achieve ultrafast recovery times and higher forward current. Its soft recovery characteristics and high reliability suit for wide industrial applications.

V_R	1200	V
I_F	15	A
$P_D(T_C=25^\circ\text{C})$	110	W
$V_{F,type.}$	1.3	V

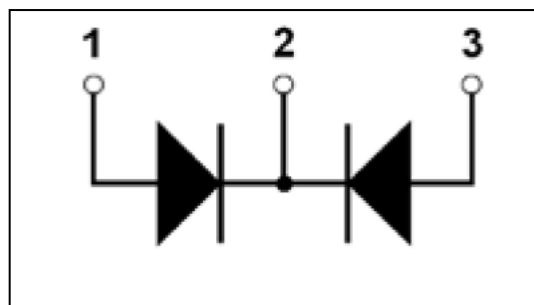
Features :

- Revolutionary semiconductor material - SiC
- No reverse recovery current / No forward recovery
- Temperature independent switching behavior
- Low forward voltage even at high operating temperature
- Tight forward voltage distribution
- Excellent thermal performance
- Extended surge current capability
- Specified dv/dt ruggedness



Applications:

- Solar inverters
- PFC
- Plating Power Supply
- Motor drives
- Ultrasonic Cleaner and Welder
- Converter & Chopper
- UPS



- **Absolute** ($T_C=25^\circ\text{C}$ unless otherwise specified) :

Symbol	Parameter	Test conditions	Rating	Units
V_R	Maximum D.C. Reverse Voltage		1200	V
V_{RRM}	Maximum Repetitive Reverse Voltage		1200	V
$I_{F(AV)}$	Average Forward Current	$T_C=155^\circ\text{C}$, Per Diode	5	A
		$T_C=135^\circ\text{C}$, Per Diode	8	A
		$T_C=25^\circ\text{C}$, Per Package	18	A
$I_{F(RMS)}$	RMS Forward Current	$T_C=25^\circ\text{C}$, $t_p=10\text{ms}$, Half Sine Wave, $D=0.3$	50	A
I_{FSM}	Non-Repetitive Surge Forward Current	$T_C=25^\circ\text{C}$, $t_p=10\text{ms}$, Half Sine Wave	100	A
P_D	Power Dissipation	$T_C=25^\circ\text{C}$	110	W
T_J	Junction Temperature		-55 to +175	$^\circ\text{C}$
T_{STG}	Storage Temperature Range		-55 to +175	$^\circ\text{C}$
Torque	Module-to-Sink	Recommended (M3)	1.1	Nm
$R_{\theta JC}$	Thermal Resistance	Junction-to-Case	1.37	$^\circ\text{C/W}$



10G1200B47

无锡光磊电子科技有限公司

GL SiC Schottky Diode

Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified) :

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I_{RM}	Reverse Leakage Current	$V_R = 1200\text{V}$	--	--	100	μA
		$V_R = 1200\text{V}, T_J = 175^\circ\text{C}$	--	--	200	μA
V_F	Forward Voltage	$I_F = 5\text{A}$	--	1.5	1.8	V
		$I_F = 5\text{A}, T_J = 175^\circ\text{C}$	--	2.0	--	V
Q_C	Total capacitive charge	$V_R = 800\text{V}, T_J = 150^\circ\text{C}$ $Q_C = \int_0^{V_R} C(V) dV$		38		nC
C	Total Capacitance	$V_R = 1\text{V}, f = 1\text{MHz}$	480		550	pF
		$V_R = 400\text{V}, f = 1\text{MHz}$	35		45	pF
		$V_R = 800\text{V}, f = 1\text{MHz}$	34		40	pF

Characteristics Curve :

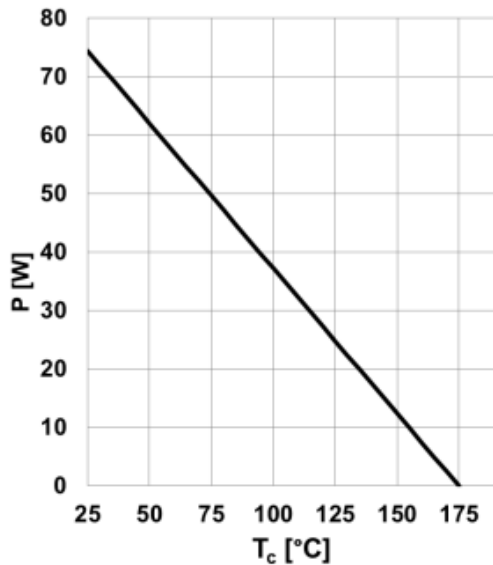


Figure 1. Power dissipation per leg as function of case temperature, $P_{tot}=f(T_c)$, $R_{th(j-c),max}$

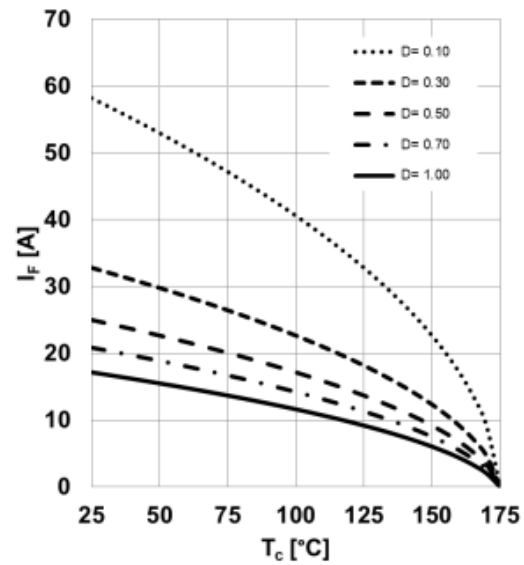


Figure 2. Diode forward current per leg as function of case temperature, $I_F=f(T_c)$, $T_j \leq 175^\circ\text{C}$, $R_{th(j-c),max}$, parameter D =duty cycle, V_{th} , R_{diff} @ $T_j=175^\circ\text{C}$

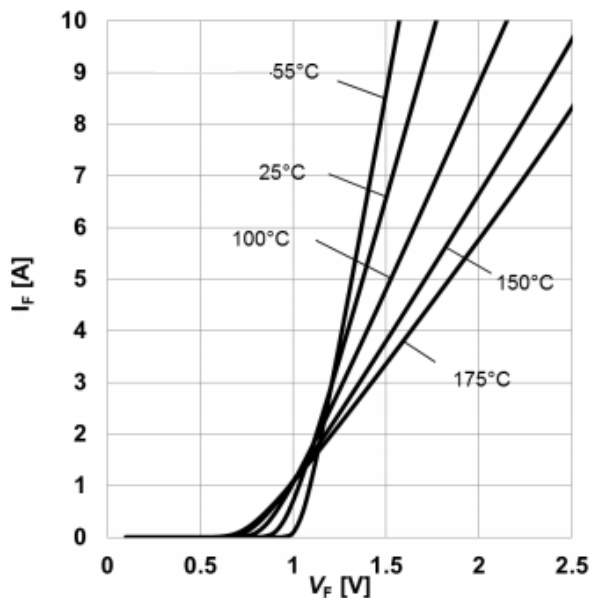


Figure 3. Typical forward characteristics per leg, $I_F=f(V_F)$, $t_p=10\text{ }\mu\text{s}$, parameter: T_j

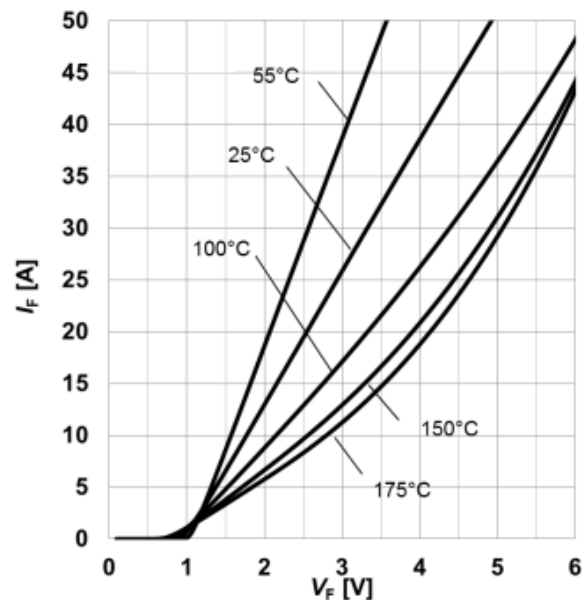


Figure 4. Typical forward characteristics in surge current per leg, $I_F=f(V_F)$, $t_p=10\text{ }\mu\text{s}$, parameter: T_j

GL SiC Schottky Diode

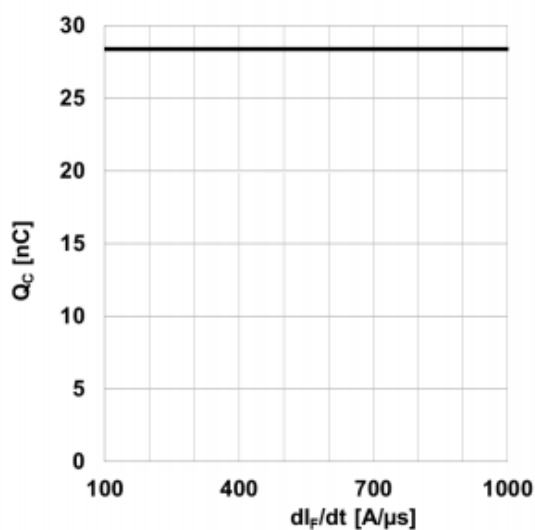


Figure 5. Typical capacitive charge per leg as function of current slope¹, $Q_C=f(di_F/dt)$, $T_J=150^\circ\text{C}$
1) guaranteed by design.

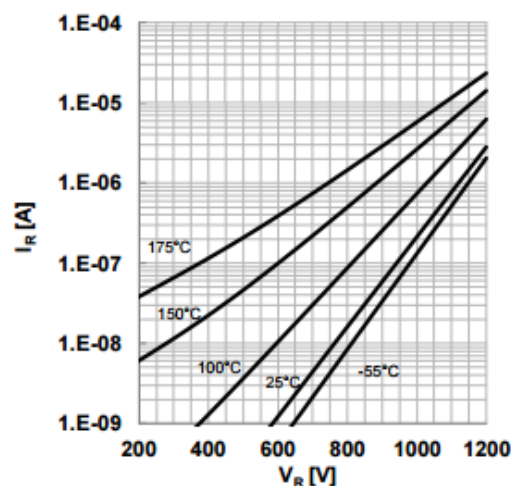


Figure 6. Typical reverse characteristics per leg, $I_R=f(V_R)$, parameter: T_J

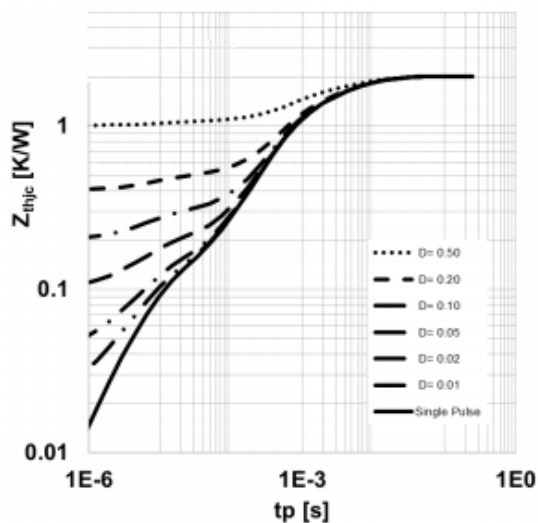


Figure 7. Max. transient thermal impedance per leg, $Z_{thjc}=f(t_p)$, parameter: $D=t_p/T$

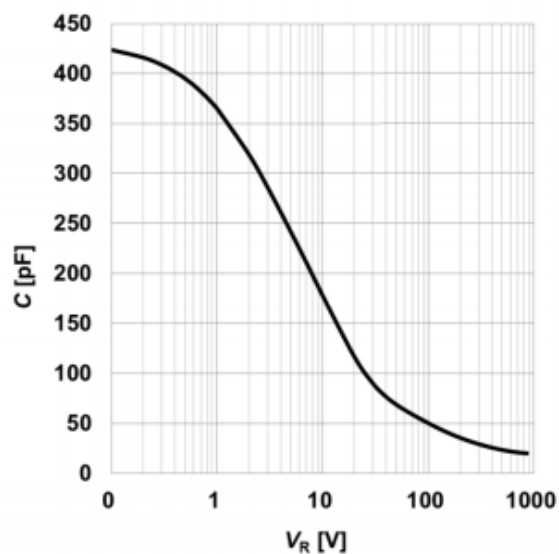


Figure 8. Typical capacitance per leg as function of reverse voltage, $C=f(V_R)$; $T_J=25^\circ\text{C}$; $f=1\text{ MHz}$

Company : Wuxi Guang Lei electronic technology co., LTD

TEL : 13961734102Mr.yuan